## MLX91208

#### IMC-Hall<sup>®</sup> Current Sensor



#### **1. Features and Benefits**

- IMC-Hall<sup>®</sup> Technology
- Very high sensitivity due to Integrated Magnetic Concentrator (IMC-Hall<sup>®</sup>)
- Programmable high speed current sensor IC
- Wideband: DC to 250kHz
- Short response time 3us
- Programmable linear transfer characteristic
- Selectable Analog ratiometric output
- SOIC8 package RoHS compliant
- Lead free component, suitable for lead free soldering profile 260°C (target), MSL3
- AEC-Q100 Automotive Qualified

#### 2. Application Examples

- Inverter HEV and EV
- BLDC motor current monitoring
- Smart fuse (over-current detection)
- AC/DC Converters
- DC/AC Converter (inverter)
- DC/DC switched mode power supply

#### 3. Description

The MLX91208 is a monolithic sensor IC featuring the IMC-Hall<sup>®</sup> technology. Conventional planar Hall technology is only sensitive to the flux density applied orthogonally to the IC surface. The IMC-Hall<sup>®</sup> current sensor is sensitive to the flux density applied parallel to the IC surface. This is obtained through an Integrated Magneto-Concentrator (IMC-Hall<sup>®</sup>) which is deposited on the CMOS die (as an additional back-end step). The IMC-Hall<sup>®</sup> technology is automotive qualified.

The product is a single chip Hall sensor which provides an output signal proportional to the flux density applied horizontally and is therefore suitable for current measurement. It is ideally suited as an open loop current sensor for PCB or bus bar mounting. It features small size application design and a simple construction for various current ranges from few Amperes up to 1000 Amperes.

The transfer characteristic of the MLX91208 is programmable in terms of offset, gain or temperature compensation. The linear analog output is designed for applications where a very fast response is required, such as inverter applications.



Figure 2: Block diagram



*Figure 1: Typical application of MLX91208* 



## 4. Ordering Information

Product	Temperature	Package	Option Code	Packing Form	Sensitivity Range (typ.)
ML91208	L (-40°C to 150°C)	DC	CAL - 000	TU/RE	100-700mV/mT (250mV/mT)
ML91208	L (-40°C to 150°C)	DC	CAH - 000	TU/RE	50-350mV/mT (100mV/mT)
ML91208	L (-40°C to 150°C)	DC	CAV - 000	TU/RE	30-200mV/mT (40mV/mT)
ML91208	L (-40°C to 150°C)	DC	CAV - 001	TU/RE	30-200mV/mT (60mV/mT)

Table 1: Ordering Information

#### Legend:

Temperature Code:	L	- from -40°C to 150°C
Package Code:	DC	- for SOIC-8 package
	xxL	- Low field version
Option Code:	ххН	- High field version
	ххV	- Very high field version
	RE	- for Reel
Packing Form Code:	TU	- for Tube
Ordering Example:	"MLX912	08LDC-CAH-000-RE"

Table 2: Legend

## 5. Glossary of Terms

Terms	Definition
Tesla	Units for the magnetic flux density, 1 mT = 10 Gauss
тс	Temperature Coefficient in ppm/deg C
NC	Not Connected
ADC	Analog to Digital Converter
DAC	Digital to Analog Converter
LSB	Least Significant Bit
MSB	Most Significant Bit
DNL	Differential Non Linearity
INL	Integral Non Linearity
IMC	Integrated Magneto Concentrator (IMC-HALL®)
PTC	Programming Through Connector

Table 3: Glossary of terms



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## 6. Absolute Maximum Ratings

Parameters	Symbol	Value	Units
Positive Supply Voltage (overvoltage)	Vdd	+10	V
Reverse Supply Voltage Protection		-0.3	V
Positive Output Voltage		+10	V
Output Current	lout	±70	mA
Reverse Output Voltage		-0.3	V
Reverse Output Current		-50	mA
Package Thermal Resistance (junction-to-ambient) θ <sub>ja</sub> is defined according JEDEC 1s0p board	$ heta_{ja}$	174	°C/W
Operating Ambient Temperature Range	ТА	-40 to 150	°C
Storage Temperature Range	TS	-55 to 165	°C
Magnetic Flux Density		±3	Т
Maximum Junction Temperature	Tj,max	-55 to 155	°C
ESD (HBM)		2	kV
Table 4. Abaabata maning and is as			

Table 4: Absolute maximum ratings

Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

## 7. Pin Definitions and Descriptions

Pin №	Name	Туре	Function
5	VDD	Supply	Supply Voltage
3	GND	Ground	Supply Voltage
1	VDEC	Digital	Digital supply voltage
4	TEST/MUST	Digital	Test and Factory calibration
6	OUT	Analog	Current sensor output
2,7,8	NC	-	Not connected / unused

#### Table 5: PIN definitions and descriptions

It is recommended to connect the unused pins to the Ground for optimal EMC performance.

## 8. General Electrical Specifications

Operating Parameters: TA = -40 to 125deg.C, Vdd = 4.5V to 5.5V, lout = -2mA to +2 mA, recommended application diagram in section 14, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Тур.	Max	Units
Nominal Supply Voltage	Vdd		4.5	5	5.5	V
Supply Current	Idd	W/o output load in application mode $T_A = -40$ to 150°C	9	12	14	mA
DC load Current	lout	Rout in range [ $6k\Omega$ , 100k $\Omega$ ]	-2		2	mA
Maximum Output Current (driving capability)	Imax	Inside this range, output voltage reaches 3%VDD and 97%VDD	-2		2	mA
Output Resistance		Vout = 50% Vdd, $R_L = 6k\Omega$		1	5	Ω
Output Capacitive Load	C <sub>load</sub>	Output amplifier is optimized for the capacitive load range.	1		10	nF
Output resistive load	$R_{load}$	Output resistive load for high linearity	6			kΩ
Output Short Circuit Current	I <sub>short</sub>	Output shorted permanent to Vdd.		Not destroyed		
		Output shorted permanent to GND.		Not destroyed		
Leakage current	l <sub>leak</sub>	High impedance mode <sup>(1)</sup> T=150°C			20	uA
Linear Output Voltage Range Vout in [10%Vdd, 90%Vdd]	$V_{out\_pd}$	pull down ≥ 10 kΩ	10		90	%Vdd
High-impedance mode levels <sup>(1)</sup>	$V_{\text{out}\_\text{HiZ}\_\text{pd}}$	pull-down R <sub>L</sub> ≤ 25 kΩ, T≤125℃			5	%Vdd
Under-voltage detection	$V_{dd\_uvd}$	Low to high voltage	3	3.3	4	V
	$V_{dd\_uvh}$	Hysteresis	0.20	0.3	0.45	V

<sup>&</sup>lt;sup>1</sup> *Refer to chapter Self-diagnostic, table 12* 



Over-voltage detection <sup>(2)</sup>	$V_{dd\_ovd}$	Low to High voltage	6.5	7.6	V
	$V_{dd\_ovh}$	Hysteresis	0.05	0.7	V
Ratiometry enable	$V_{ratio\_d}$	Low to High Voltage	4	4.50	V
detection <sup>(2)</sup>	$V_{ratio_h}$	Hysteresis	0.01	0.5	V

Table 6: General electrical parameter

(2) According to the figure below:



#### 9. Magnetic specification

#### 9.1. Low Field Version 10mT (option code xxL)

Operating Parameters TA = -40 to 125deg.C, Vdd = 4.5 V to 5.5 V, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Nominal Field Range	Bnom		-7.5		+7.5	mT
Operational Field Range <sup>(3)</sup>	Вор		-10		+10	mT
Linearity Error	NL	B in range Bop Vout in [10%VDD, 90%VDD]	-0.7		+0.7	%FS
Hysteresis, remanent Field	Br	B = Bop	-10		+10	uT
Programmable Sensitivity	S		100	250	700	mV/mT
Sensitivity programming Resolution	Sres			0.1		%

Table 7: Magnetic specification for 10mT version (low-field version)

#### 9.2. High Field Version 25mT (option code xxH)

Operating Parameters TA = -40 to 125deg.C, Vdd = 4.5 V to 5.5 V, unless otherwise specified.

Parameter	Symbol Test Condi	tions Min	Тур Мах	Units
Nominal Field Range	Bnom	-20	+20	mT
Operational Field Range <sup>(3)</sup>	Вор	-25	+25	mT

<sup>&</sup>lt;sup>2</sup> See graph below the table

<sup>&</sup>lt;sup>3</sup> Outside Bop, the IMC progressively enters saturation, yielding to an increase of the linearity error.



Linearity Error	NL	B in range Bop Vout in [10%VDD, 90%VDD]	-0.7		+0.7	%FS
Hysteresis, remanent Field	Br	B = Bop	-25		+25	uT
Programmable Sensitivity	S		50	100	350	mV/mT
Sensitivity programming Resolution	Sres			0.1		%

Table 8: Magnetic specification 25mT version (high-field version)

## 9.3. Very High Field Version 60mT (option code xxV)

Operating Parameters TA = -40 to 125deg.C, Vdd = 4.5 V to 5.5 V, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Nominal Field Range	Bnom		-50		+50	mT
Operational Field Range <sup>(3)</sup>	Вор		-60		+60	mT
Linearity Error	NL	B in range Bop Vout in [10%VDD, 90%VDD]	-0.7		+0.7	%FS
Hysteresis, remanent Field	Br	B = Bop	-60		+60	uT
Programmable Sensitivity	S	CAV-000 CAV-001	30 30	40 60	200 200	mV/mT mV/mT
Sensitivity programming Resolution	Sres			0.1		%

Table 9: Magnetic specification 60mT version (Very high-field version)

Note: The noise filter is disabled by default for all MLX91208 versions.

#### 10. Analog output specification

#### 10.1. Timing specification

Operating Parameters  $T_A = -40$  to 125deg.C, Vdd = 4.5 V to 5.5 V (unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Refresh rate	Trr		0.8	1	2	us
Step Response Time	Tresp	Delay between the input signal reaching 90% and the output signal reaching 90%, (2V step at the output, input rise time = 1µs) -Noise filter OFF -Noise filter ON		2 5	3 6	μs μs
Bandwidth	BW	-Noise filter OFF -Noise filter ON	200 120	250 150	300 180	kHz kHz



Power on Delay	TPOD	Vout =100% of FS Pull-down resistor ≤100kOhm During the Power-on delay, the output will remain within the 10% fault band at all time.		1	ms
Ratiometry Cut-off Frequency	Fratio		250		Hz

Table 10: Timing specification high speed analog output



Figure 3: Response time definition

#### 10.2. Accuracy specification

Operating Parameters  $T_A = -40$  to 125deg.C, Vdd = 4.5 V to 5.5 V (unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Thermal Offset Drift	Δ <sup>T</sup> Voq	Offset drift referred to 25°C S=40mV/mT (xxV version) S=100mV/mT (xxH version) S=250mV/mT (xxL version) Vdd=5V, TC=0±150 ppm/°C Voq=50±0.2 %Vdd	-10		+10	mV
Thermal Sensitivity Drift	ТС		-1.5	0	+1.5	% of S
RMS Output noise	N <sub>rms</sub>	S=40mV/mT (xxV version) S=100mV/mT (xxH version) S=250mV/mT (xxL version) -Noise filter OFF -Noise filter ON			10 6	mVrms mVrms
Ratiometry Error Offset	ΔVoq	Voq = 50%Vdd ΔVdd = 10%Vdd	-0.4		+0.4	% of Voq
Ratiometry Error Sensitivity	ΔS	$\Delta V dd = 10\% V dd$	-0.4		+0.4	% of S

Table 11: Accuracy-Specific Parameters



#### 10.3. Remarks to the achievable accuracy

The achievable target accuracy is dependent on user's end-of-line calibration. The resolution for the offset and offset drift calibration is better than 0.1%Vdd. Trimming capability is higher than the measurement accuracy. End-user calibration can increase the accuracy of the system.

#### 11. Programmable items

#### 11.1. Parameter table

Parameter	Bits	Factory Setting	Comment
VOQ[11:0]	12	trimmed	Quiescent output level (0 Gauss) adjustment
RG[2:0]	3	trimmed	Rough gain adjustment
FG[9:0]	10	trimmed	Fine gain adjustment
ENRATIO	1	1	Ratiometry enablement
TC1[7:0]	8	trimmed	Adjustment of the first order temperature compensation of the magnetic sensitivity
TC2HOT[4:0]	5	trimmed	Adjustment of the extra temperature compensation of the magnetic sensitivity at high temperature
TC2COLD[4:0]	5	trimmed	Adjustment of the extra temperature compensation of the magnetic sensitivity at low temperature
OFFDR2C[5:0]	6	trimmed	Adjustment of the offset drift at low temperature after the VGA
OFFDR2H[5:0]	6	trimmed	Adjustment of the offset drift at high temperature after the VGA
NOISEFILT	1	0	Noise filter enablement
ID[47:0]	48	Programmed	Melexis traceability ID

Table 12: Customer programmable items

#### 11.2. Sensitivity programming (RG, FG)

The sensitivity can be programmed from 50 to 350mV/mT (high field version) or 100 to 700mV/mT (low field version), with the ROUGHGAIN (3 bits) and FINEGAIN (10 bits) parameters.

#### 11.3. Offset / output quiescent voltage programming (VOQ)

The offset is programmable with 12 bits in 1.5 mV steps over the full output range. This corresponds to a calibration resolution of 0.03 %VDD.

The typical step size would be 5V/4096 = 1.22 mV, but the actual step size can differ from the nominal value because of internal gain tolerance. A maximum step size of 1.5 mV is guaranteed.

**Note:** for optimal performance over temperature, the VOQ should be programmed in the range from 2 to 3V.



#### 11.4. Output ratiometry (ENRATIO)

The ratiometry of the output versus the supply can be disabled by setting this bit to 0.

**Note:** for optimal performance over temperature, the ratiometry setting should not be changed on customer side. By default, this setting is enabled during final test calibration.

#### 11.5. Sensitivity temperature drift programming (TC1ST, TC2ND\_COLD, TC2ND\_HOT)

First order sensitivity temperature drift can be trimmed with TC1. The programming resolution is 40ppm/K.

Second order sensitivity temperature drift can be trimmed with TC2COLD and TC2HOT. The programming resolution is  $2ppm/K^2$  for TC2COLD and  $0.6ppm/K^2$  for TC2HOT. The second order can also be seen as third order correction since cold and hot sides are independently adjusted.

**Note:** for optimal performance over temperature, the first order sensitivity drift compensation (TC1ST) should not exceed ±250ppm/K.

#### 11.6. Offset temperature drift programming (OFFDR2C, OFFDR2H)

Offset temperature drift caused by the output amplifier can be compensated with these two parameters. This first order correction is done independently for temperatures over and below 25°C.

**Note:** Two additional parameters (OFFDR1C, OFFDR1H) are calibrated by Melexis to compensate for the offset temperature drift caused by the Hall element (before the variable gain amplifier). These parameters should not be adjusted on customer-side.

#### 11.7. Noise filter (NOISEFILT)

Setting this bit to 1 enables the noise filter, reducing noise and increasing response time.

#### 11.8. Identification code (ID)

48 bits programmed identification code.



## 12. Self-diagnostic

The MLX91208 provides self-diagnostic features to detect internal memory errors and over- / under-voltage. Those features increase the robustness of the IC functionality, as they prevent the IC from providing erroneous output signal in case of internal or external failure modes.

Error	Action	Effect on Outputs	Remarks
Calibration Data CRC Error (at power up and in normal working mode)	Fault mode	High Impedance mode	Pull down resistive load, Diagnostic Low
Power On delay		High Impedance mode	1ms max in high impedance followed by settling
Undervoltage Mode	IC is reset	High Impedance mode	300mV Hysteresis (typical)
Overvoltage detection	IC is reset	High Impedance mode	500mV Hysteresis (typical)

Table 13: Self diagnostic

### 13. Application information

Please refer to our current sensor reference design guide for more application information:

https://www.melexis.com/en/documents/documentation/application-notes/application-note-currentsensor-design-guide



## 14. Recommended Application Diagrams

#### 14.1. Resistor and capacitor values

Part	Description	Value	Unit
C1	Supply capacitor, EMI, ESD	100	nF
C2	Decoupling, EMI, ESD	2-10 (4)	nF
C3	Decoupling, EMI, ESD	47	nF
R1	Pull down resistor	6-100	kΩ

Table 14: Resistor and capacitor values

#### 14.2. Pull-down resistor for diagnostic low



Figure 7: Diagnostic low/ Pull-down resistors

<sup>4</sup> 10nF is recommended for better EMC and ESD performance



## 15. Typical performance



Figure 9: Thermal sensitivity drift.





Figure 11: Linearity error for all versions.



Figure 12: Response time with noise filter OFF.



*Figure 13: Response time with noise filter ON.* 



# 16. Standard information regarding manufacturability of Melexis products with different soldering processes

Melexis devices are qualified using state-of-the-art practices in accordance with automotive and environmental requirements.

Through qualifications, various soldering techniques are considered; please refer to "Soldering recommendations for Melexis products" for more information:

https://www.melexis.com/en/documents/documentation/application-notes/application-note-solderingrecommendations

For components normally soldered using Surface Mounted Device techniques (eg: Reflow process), Melexis has defined and qualified Moisture Sensitivity Level and Peak Temperature in accordance with the Jedec J-STD-020 standard. Delivered material is conditioned accordingly. Moisture Sensitivity Level and Peak Temperature information can be found on the label identifying the material.

In case you intend to use a reflow soldering process for through hole devices (Melexis' package codes: SA, UA, VA, VK, VM), please contact Melexis to verify your soldering process compatibility.

The application of Wave Soldering for SMD's is allowed only after consulting Melexis regarding assurance of adhesive strength between device and board.

Based on Melexis commitment to environmental responsibility, Europe legislations (Direction on the Restriction of the Use of Certain Hazardous substances, RoHS) and customer requests, Melexis has deployed Pb free leadfinish (typically Matte Tin) on all ASSP products.

For through hole devices (Melexis' package codes: SA, UA, VA, VK, VM) Trim&Form, please refer to "Trim & Form recommendations for Melexis products" for more information:

(http://www.melexis.com/Assets/Trim\_and\_form\_recommendations\_DownloadLink\_5565.aspx)

#### 17. ESD Precautions

Electronic semiconductor products are sensitive to Electro Static Discharge (ESD).

Always observe Electro Static Discharge control procedures whenever handling semiconductor products.

ESD HBM robustness is 2kV on external pins according to AEC-Q100-002 REV-D.



## 18. Package information

#### 18.1. SOIC-8 Package Dimensions



Figure 14: SOIC-8 Package dimensions

#### 18.2. SOIC-8 Pinout and Marking



Figure 15: SOIC-8 Pinout and marking (Low Field, High Field and Very High Field version)



#### 18.3. SOIC-8 Hall plate position



Figure 16: SOIC-8 Hall Plate positioning

#### 18.4. SOIC-8 IMC Position and magnetic sensitive direction



Figure 17: IMC position and geometry for low-field version



Figure 18: IMC position and geometry high-field version



Figure 19: IMC position and geometry very high-field version



#### 19. **Contact**

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